

Application Data Sheet

Application Information

Application Type::	Regular
Subject Matter::	Utility
Suggested Classification::	
Suggested Group Art Unit::	
CD-ROM or CD-R?::	None
Number of CD disks::	
Number of Copies of CDs::	
Sequence Submission?::	None
Computer Readable Form (CRF)::	No
Number of copies of CRF::	0
Title::	WAFER POLISHING METHOD AND WAFER POLISHING APPARATUS IN SEMICONDUCTOR FABRICATION EQUIPMENT
Attorney Docket Number::	8017-1104
Request for Early Publication?::	No
Request for Non-Publication?::	No
Suggested Drawing Figure::	1
Total Drawing Sheets::	4
Small Entity?::	No
Latin Name::	
Variety Denomination Name::	
Petition Included?::	No
Petition Type::	
Licensed US Gov't Agency::	
Contract or Grant Numbers::	
Secrecy Order in Parent Appl.?::	No

Applicant Information

Applicant Authority Type:: Inventor
Primary Citizenship Country:: JAPAN
Status:: Full Capacity
Given Name:: NORIYUKI
Middle Name::
Family Name:: SAKUMA
City of Residence:: TOKYO
State or Province of
Residence::
Country of Residence:: JAPAN
Street of Mailing C/O ELPIDA MEMORY, INC.
Address:: 2-1, YAESU 2-CHOME, CHUO-KU
City of Mailing Address:: TOKYO
State or Province of Mailing Address::
Country of Mailing Address:: JAPAN
Postal or Zip Code of Mailing Address::

Applicant Authority Type:: Inventor
Primary Citizenship Country:: JAPAN
Status:: Full Capacity
Given Name:: KINJI
Middle Name::
Family Name:: TSUNENARI
City of Residence:: TOKYO
State or Province of
Residence::
Country of Residence:: JAPAN
Street of Mailing C/O ELPIDA MEMORY, INC.
Address:: 2-1, YAESU 2-CHOME, CHUO-KU
City of Mailing Address:: TOKYO
State or Province of Mailing Address::
Country of Mailing Address:: JAPAN

Postal or Zip Code of Mailing Address::

Correspondence Information

Correspondence Customer 000466

Number::

Representative Information

Representative Customer	000466
Number::	

Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::

Foreign Priority Information

Country::	Application Number::	Filing Date::	Priority Claimed::
JAPAN	2002-312542	10/28/02	Yes

Assignment Information

Assignee Name::

Street of Mailing Address::

City of Mailing Address::

State or Province of Mailing Address::

Country of Mailing Address::

Postal or Zip Code of Mailing Address::